



EGF15A THRU EGF15M

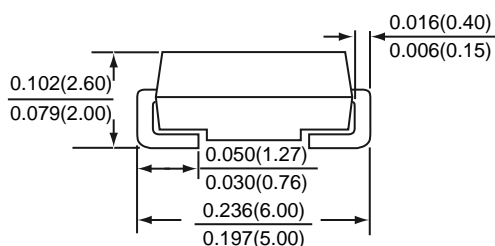
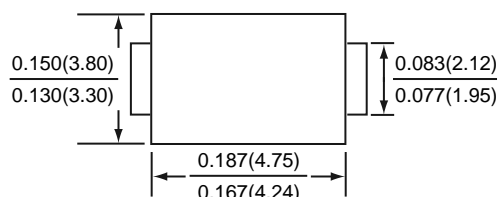
SURFACE MOUNT GLASS PASSIVATED JUNCTION HIGH EFFICIENT RECTIFIER

Reverse Voltage - 50 to 1000 Volts

Forward Current - 1.5 Amperes

PATENTED

DO-214AA



*Dimensions in inches and (millimeters)

SUPEREX II™

FEATURES

- * GPRC (Glass Passivated Rectifier Chip) inside
- * Glass passivated cavity-free junction
- * Ideal for surface mount automotive applications
- * Superfast recovery time for high efficiency
- * Built-in strain relief
- * Easy pick and place
- * High temperature soldering guaranteed: 260°C/10 seconds, at terminals
- * Plastic package has Underwriters Laboratory Flammability Classification 94V-0

MECHANICAL DATA

Case : JEDEC DO-214AA molded plastic over passivated chip
Terminals : Solder plated , solderable per MIL-STD-750, Method 2026
Polarity : Color band denotes cathode end
Mounting Position : Any
Weight : 0.003 ounces , 0.093 gram

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.	SYMBOLS	EGF15								UNITS
		A	B	D	F	G	J	K	M	
Maximum repetitive peak reverse voltage	VRRM	50	100	200	300	400	600	800	1000	Volts
Maximum RMS voltage	VRMS	35	70	140	210	280	420	560	700	Volts
Maximum DC blocking voltage	VDC	50	100	200	300	400	600	800	1000	Volts
Maximum average forward rectified current at TA=75°C	I (AV)	1.5								Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	50					45			Amps
Maximum instantaneous forward voltage at 1.5 A	VF	1.0				1.25		1.7		Volts
Maximum DC reverse current at rated DC blocking voltage	IR	5					80			uA
Maximum reverse recovery time (NOTE 1)	trr	50					75			nS
Typical junction capacitance (NOTE 2)	CJ	35								pF
Typical thermal resistance (NOTE 3)	RθJA RθJL	75 20								°C / W
Operating junction and storage temperature range	TJ,TSTG	-65 to +175					-55 to +150			°C

NOTES : (1) Reverse recovery test condition : IF 0.5A, IR=1.0A, Irr=0.25A
 (2) Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts
 (3) Thermal resistance from junction to ambient and from junction to lead P.C.B. mounted on 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas.

RATINGS AND CHARACTERISTIC CURVES EGF15A THRU EGF15M

FIG.1 - FORWARD CURRENT DERATING CURVE

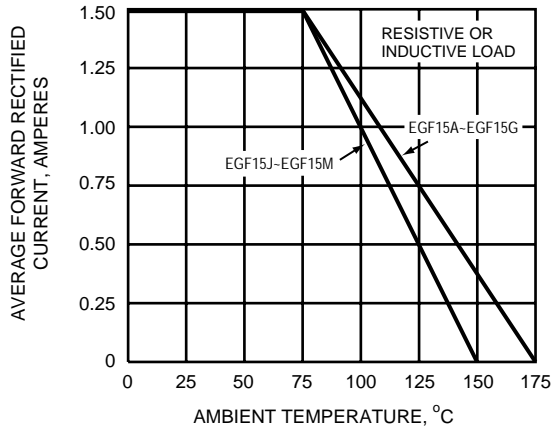


FIG.2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

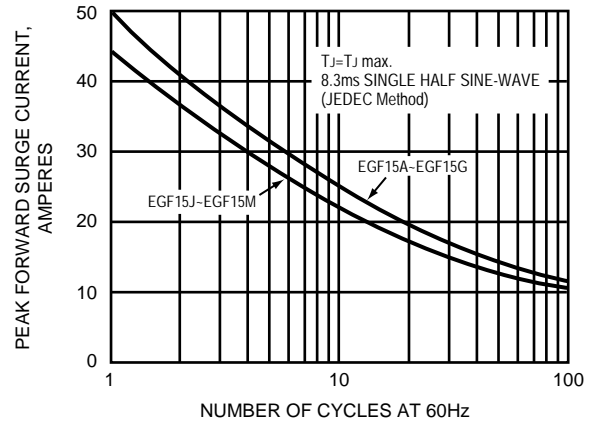


FIG.3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

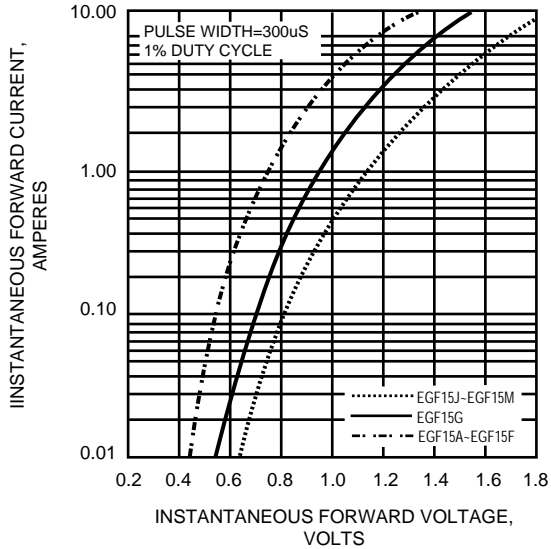


FIG.4 - TYPICAL REVERSE CHARACTERISTICS

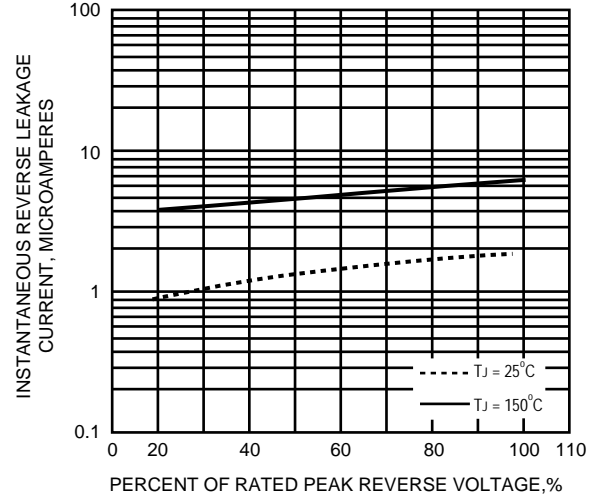


FIG.5 - TYPICAL JUNCTION CAPACITANCE

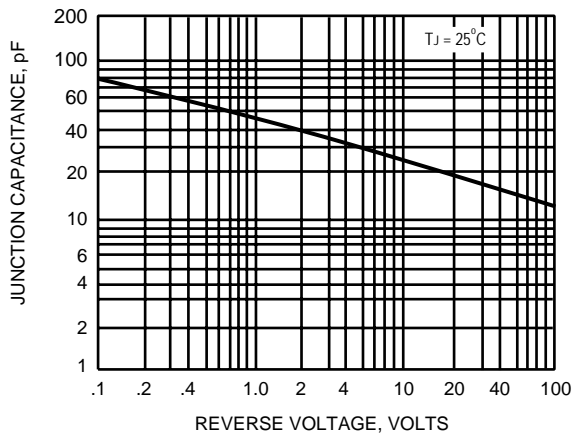


FIG.6 - TYPICAL TRANSIENT THERMAL IMPEDANCE

